Infineon at a Glance

- Top 10 semiconductor company
- FY 1999 sales €4,237m, + 33% vs. FY 1998
- Earnings turn-around achieved in FY 1999
- Very strong 1st half FY: sales + 68%, EBIT +€543m
- One of the fastest growing major semiconductor companies
  27,000 employees
- World class manufacturing sites on three continents
  (four 8 inch fabs ramping 0.18µm)
- 21 R&D sites worldwide
- Rich IP-portfolio consisting of more than 25,000 patents
- World class customer base of around 40 global key accounts
Innovation Driver for Our Target Applications

Communication
- Mobile communication
- Internet infrastructure and terminals
- Telecom infrastructure and terminals

Automotive
- Airbags, ABS
- Engine management
- Navigation systems

Computers
- Faster and denser memories

Advanced Security Systems
- Banking and GSM cards
- Biometric sensors (e.g. FingerTIP™)
- High performance encryption ICs
Leading Position in our Key Markets

Mobile Communication
- #1 in Radio-Frequency-ICs
- #2 in Baseband-ICs
- #1 in Chipsets for digital cordless Applications like DECT, WDCT, Bluetooth

Communication & Multimedia
- #1 in ISDN
- Leading Position in traditional telecommunication
- rapid growth in data communication

Automotive & Industrial
- #2 in automotive semiconductors (without car radio)
- Leading Market Position in Europe in
  - engine management with micro-controllers
  - Airbag and ABS with smart power ICs
- Leading Market Position in Industrial Drives

Security & Chipcard ICs
- World Market Leader for Chipcard ICs (more than 27 billion pieces shipped over the last 10 years)
- Leading Position in High Growth Applications such as GSM, telecoms and banking

Memory Products
- #5 in DRAMs
- #1 in 256 M
- Leader in embedded DRAM and 300mm technology
More than 45% of revenues generated in communications
Wireless Systems Division
Wireless Systems Division
Organization

Guenter Weinberger

<table>
<thead>
<tr>
<th>Sales &amp; Marketing</th>
<th>Silicon Discretes</th>
<th>GaAs &amp; Sensors</th>
<th>Linear ICs</th>
<th>Wireless Baseband</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dr. H.-J. Dittloff</td>
<td>Th. Poliakowski</td>
<td>Dr. E. Pettenpaul</td>
<td>M. van Riek</td>
<td>Dr. H.-J. Eul</td>
</tr>
<tr>
<td>• Account Teams</td>
<td>• RF-Transitors</td>
<td>• LNA</td>
<td>• Cellular ICs</td>
<td>• Cellular ICs</td>
</tr>
<tr>
<td>• Sales Operations</td>
<td>• RF-Diodes</td>
<td>• PA</td>
<td>• Cordless ICs</td>
<td>• Cordless ICs</td>
</tr>
<tr>
<td>• Account Marketing</td>
<td>• RF-MMICs</td>
<td>• MMICs</td>
<td>• Custom Products</td>
<td></td>
</tr>
<tr>
<td>• Processes &amp; Info.</td>
<td>• AF-Trans. and Diodes</td>
<td>• Sensors</td>
<td>• Consumer ICs</td>
<td></td>
</tr>
<tr>
<td>• System Marketing</td>
<td></td>
<td>• Smart Sensors</td>
<td></td>
<td></td>
</tr>
<tr>
<td>• System Projects</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Bus. Operations
NA / AP / Japan

<table>
<thead>
<tr>
<th>Business Administration</th>
<th>Operations</th>
<th>Technology &amp; Innovation</th>
<th>Quality Management</th>
<th>Frontend Locations</th>
<th>Backend Locations</th>
</tr>
</thead>
<tbody>
<tr>
<td>M. Ruth</td>
<td>W. Heidenreich</td>
<td>S. Hein</td>
<td>H. Broemmel</td>
<td>Munich</td>
<td>Regensburg</td>
</tr>
<tr>
<td>• Controlling</td>
<td>• Logistics</td>
<td>• 3G Systems</td>
<td>• Quality Management</td>
<td>• Regensburg</td>
<td>• Malacca</td>
</tr>
<tr>
<td>• Business Admin.</td>
<td>• Order Processing</td>
<td>• Technologies</td>
<td>Business Units</td>
<td>• Dresden</td>
<td>• Singapore</td>
</tr>
<tr>
<td>• Business Units</td>
<td>• Production Management</td>
<td>• Emerging Applications</td>
<td>Analytic Processes</td>
<td>• Esonnes</td>
<td>• Batam</td>
</tr>
<tr>
<td>• Information System and Services</td>
<td></td>
<td></td>
<td>• Reliability and Test</td>
<td>• Villach</td>
<td></td>
</tr>
</tbody>
</table>

Never stop thinking
Wireless Systems
Capturing The Best Designers - Worldwide
Wireless Division
Production sites for world-wide partnership

**CoC:** Center of Competence

- **Essonnes:** 8" Wafer Fab
- **Munich Balanstr.:** Headquarter 4" / 5" Wafer Fab
- **Munich Perlach:** CoC BiCMOS 6" Wafer Fab
- **Villach:** CoC Sensors 5" / 6" Wafer Fab
- **Regensburg:** CoC Automatisation & Pilot Productions 6" Wafer Fab
- **Dresden:** 8" Wafer Fab
- **Malacca:** Assembly & Testing Discretes
- **Wuxi:** Assembly & Testing IC’s and Discretes
- **Singapore:** Assembly & Testing IC’s

**Wireless Division**
Production sites for world-wide partnership
Wireless Systems

! Complete Product Scope with System Vision !
Wireless Systems
Application Focus
Wireless Systems
Customized Business Offers

- Business Offers
  - Foundry Offer
    - Leading Technologies
    - IP
    - ASIC Flow
  - System Support Solution Offer
    - Customized support and solution
  - ICs and Discretes Offer
    - Products with System Vision
  - System Modules Offer
    - Application optimized solution

Bluetooth
GSM
Wireless Systems
RF ICs Track Record - RF Business

- 1st RF IC Bluetooth in mass production
- 1st single Chip DECT Transceiver
- 1st complete RF solution for WDCT
- 1st single chip GSM transmitter
- 1st single GSM chip receiver

1980 - 2000
Wireless Systems
BB ICs Product Track Record

World’s 1st 0,25 µm single-chip GSM solution (E-Gold) - opens the era of new architecture

- World’s 1st 0,25 µm GSM chipset (Hi-Gold V4)
- E-Gold 100+: 1st fully GPRS-capable integrated solution for GSM generation 2.5 (in 0,18 µm)
- E-Gold+: single-chip adaptive multi-rate IC and power management IC
Cellular Business
System Aspects - Evolution of Handsets

1998
~ 450 components

1999
~ 350 components

2000
~ 180 components

2001
~ 150 components

2002
~ 100 components

- 3 Chip RF
- 1 Chip RF
- 1 Chip RF
- 1 Chip RF

- HGOLD
- SMARTi
- SMARTi
- SMARTi DC

- Pwr Mgt
- SRAM
- Flash
- Pwr Mgt
- Flash
- Flash
- Pwr Mgt

- CGY98
- SMARTi
- SMARTi
- E-GOLD

- VCO
- VCO
- VCO
- VCO

- CGY99
- SMARTi
- SMARTi
- SMARTi

Increase of processing power

MIPS